



Title of Change:	AR1335 CFA Manufacturing site change.	
Proposed first ship date:	1 October 2018	
Contact information:	Contact your local ON Semiconductor Sales Office or Jason.Whetstone@onsemi.com	
Samples:	Samples should be available after completion of qualification (end of June 2018). Contact your local ON Semiconductor Sales Office.	
Type of notification:	<p>This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.</p> <p>The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.</p>	
Change Part Identification:	Affected parts will be identified with a date code. The date code information will be updated in the FPCN forecast to be published around	
Change category:	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<div style="display: flex; justify-content: space-between;"> <div> <input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change </div> <div> <input type="checkbox"/> Material Change <input type="checkbox"/> Product specific change </div> <div> <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____ </div> </div>	
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: Toppan Kumomoto Toppan Chungwa Electronic
Description and Purpose: <p>This is an initial product change notification to inform customers about color the filter array wafer fab site change from Toppan Kumomoto (Japan) to Toppan Chungwa Electronic (TCE) Taiwan on AR1335 products. This is not a site addition for second source but a one-time permanent change.</p> <p>There is no change in form, fit or function.</p> <p>The changes are being done within current process and technology limits to meet product datasheet specifications. The manufacturing flow and the CFA material in the proposed site is identical to that in current and there are no additional changes in backend assembly or test flow i.e. the proposed change is fully compatible with current flow.</p> <p>This change is being initiated and executed by the external foundry supplier (Toppan) to support customers with better capacity and quality.</p>		

**Qualification Plan:**

QV DEVICE NAME: AR1335

PACKAGE: CSP

Test	Specification	Condition	Interval
HTSL	JESD22-A103	Ta= 150°C	504 hrs
TC	JESD22-A104	Ta= -55°C to +125°C	500 cyc
THS	JEITA ED4701-100 Method 103	60°C, 90% RH, unbiased	1008hrs
PC	J-STD-020 JESD-A113	MSL 4 @ 250 °C	

Estimated date for qualification completion: 31 July 2018

List of Affected Standard Parts:

Part Number	Qualification Vehicle
AR1335CSSC32SMD10	AR1335CSSC11SMKA0-CP
AR1335CSSC32SMD20	
AR1335CSSC32SMD20-HW	
AR1335CSSM32SMD20	
AR1335CSSC11SMD20	
AR1335CSSC11SMKA0-CP	
AR1335CSSC11SMKA0-CP1	
AR1335CSSC11SMKA0-CR	
AR1335CSSC11SMKA0-CR1	
AR1335CSSM11SMD20	
AR1335HS2C11SMAA0-DPBR	
AR1335HS2C11SMAA0-DRBR	
AR1335HSSC11SMAA0-DPBR	
AR1335PDSC32SMD10	
AR1335PDSC32SMD20	

Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle
AR1335CSSC11SMKA0-CP		AR1335CSSC11SMKA0-CP
AR1335CSSC11SMKA0-CP1		AR1335CSSC11SMKA0-CP
AR1335CSSC11SMKA0-CR		AR1335CSSC11SMKA0-CP
AR1335CSSC11SMKA0-CR1		AR1335CSSC11SMKA0-CP
AR1335HSSC11SMAA0-DPBR		AR1335CSSC11SMKA0-CP